

DRAM

MT4C1004J

FEATURES

- 1,024-cycle refresh distributed across 16ms (MT4C1004J) or 128ms (MT4C1004J L only)
- Industry-standard pinout, timing, functions and packages
- High-performance CMOS silicon-gate process
- Single +5V $\pm 10\%$ power supply
- All inputs, outputs and clocks are TTL-compatible
- Refresh modes: RAS#-ONLY, CAS#-BEFORE-RAS# (CBR), HIDDEN; optional Extended
- FAST PAGE MODE access cycle

OPTIONS

- Timing
60ns access

- Packages
Plastic SOJ (300 mil)
Plastic TSOP (300 mil)

- Refresh Rate
Standard 16ms period
Extended 128ms period

- Part Number Example: MT4C1004JDJ-6 L

MARKING

-6

DJ

TG

None

L

KEY TIMING PARAMETERS

SPEED	t_{RC}	t_{RAC}	t_{PC}	t_{AA}	t_{CAC}	t_{RP}
-6	110ns	60ns	35ns	30ns	15ns	40ns

GENERAL DESCRIPTION

The MT4C1004J(L) is a randomly accessed, solid-state memory containing 4,194,304 bits organized in a x1 configuration. During READ or WRITE cycles, each bit is uniquely addressed through the 22 address bits, which are entered 11 bits (A0-A10) at a time. RAS# is used to latch the first 11 bits and CAS# the latter 11 bits. READ and WRITE cycles are selected with the WE# input. A logic HIGH on WE# dictates READ mode while a logic LOW on WE# dictates WRITE mode. During a WRITE cycle, data-in (D) is latched by the falling edge of WE# or CAS#, whichever occurs last. If WE# goes LOW prior to CAS# going LOW, the output pin remains open (High-Z) until the next CAS# cycle. If WE# goes LOW after data reaches the output pin, data-out (Q) is activated and retains the selected cell data as long as CAS# remains LOW (regardless of WE# or RAS#). This late WE# pulse results in a READ WRITE cycle.

PIN ASSIGNMENT (Top View)

20/26-Pin SOJ (DA-1)

D	1	26	Vss
WE#	2	25	Q
RAS#	3	24	CAS#
NC	4	23	NC
*A10	5	22	A9
A0	9	18	A8
A1	10	17	A7
A2	11	16	A6
A3	12	15	A5
Vcc	13	14	A4

20/26-Pin TSOP (DB-1)

D	1	26	Vss
WE#	2	25	Q
RAS#	3	24	CAS#
NC	4	23	NC
*A10	5	22	A9
A0	9	18	A8
A1	10	17	A7
A2	11	16	A6
A3	12	15	A5
Vcc	13	14	A4

*Address not used for RAS#-ONLY REFRESH

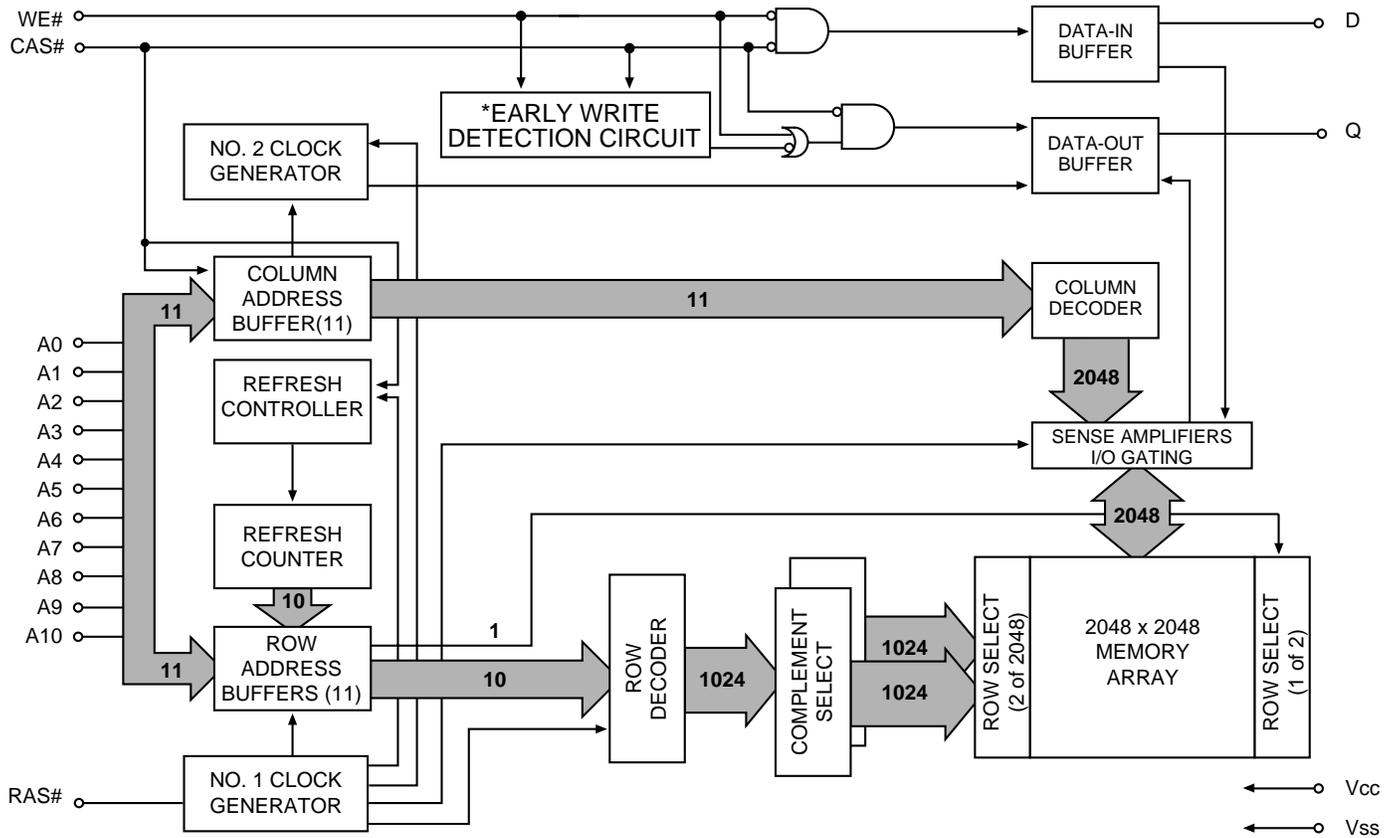
Note: The # symbol indicates signal is active LOW.

FAST PAGE MODE

FAST PAGE MODE operations allow faster data operations (READ, WRITE or READ-MODIFY-WRITE) within a row-address-defined (A0-A10) page boundary. The FAST PAGE MODE cycle is always initiated with a row address strobed-in by RAS# followed by a column address strobed-in by CAS#. CAS# may be toggled-in by holding RAS# LOW and strobing-in different column addresses, thus executing faster memory cycles. Returning RAS# HIGH terminates the FAST PAGE MODE operation.

Returning RAS# and CAS# HIGH terminates a memory cycle and decreases chip current to a reduced standby level. Also, the chip is preconditioned for the next cycle during the RAS# HIGH time. Memory cell data is retained in its correct state by maintaining power and executing any RAS# cycle (READ, WRITE) or RAS# refresh cycle (RAS# ONLY, CBR, or HIDDEN) so that all 1,024 combinations of RAS# addresses (A0-A9) are executed at least every 16ms for the MT4C1004J and every 128ms for the MT4C1004J L, regardless of sequence. The CBR and extended refresh cycles will invoke the internal refresh counter for automatic RAS# addressing.

**FUNCTIONAL BLOCK DIAGRAM
FAST PAGE MODE**



***NOTE:** 1. If WE# goes LOW prior to CAS# going LOW, EW detection circuit output is a HIGH (EARLY WRITE).
2. If CAS# goes LOW prior to WE# going LOW, EW detection circuit output is a LOW (LATE WRITE).

OBSOLETE



4 MEG x 1
FPM DRAM

TRUTH TABLE

FUNCTION		RAS#	CAS#	WE#	ADDRESSES		DATA	
					t _R	t _C	D (Data-In)	Q (Data-Out)
Standby		H	H→X	X	X	X	"don't care"	High-Z
READ		L	L	H	ROW	COL	"don't care"	Data-Out
EARLY WRITE		L	L	L	ROW	COL	Data-In	High-Z
READ WRITE		L	L	H→L	ROW	COL	Data-In	Data-Out
FAST-PAGE-MODE READ	1st Cycle	L	H→L	H	ROW	COL	"don't care"	Data-Out
	2nd Cycle	L	H→L	H	n/a	COL	"don't care"	Data-Out
FAST-PAGE-MODE EARLY-WRITE	1st Cycle	L	H→L	L	ROW	COL	Data-In	High-Z
	2nd Cycle	L	H→L	L	n/a	COL	Data-In	High-Z
FAST-PAGE-MODE READ-WRITE	1st Cycle	L	H→L	H→L	ROW	COL	Data-In	Data-Out
	2nd Cycle	L	H→L	H→L	n/a	COL	Data-In	Data-Out
RAS#-ONLY REFRESH		L	H	X	ROW	n/a	"don't care"	High-Z
HIDDEN REFRESH	READ	L→H→L	L	H	ROW	COL	"don't care"	Data-Out
	WRITE	L→H→L	L	L	ROW	COL	Data-In	High-Z
CBR REFRESH		H→L	L	H	X	X	"don't care"	High-Z

ABSOLUTE MAXIMUM RATINGS*

Voltage on Any Pin Relative to V _{SS}	-1V to +7V
Operating Temperature, T _A (ambient)	0°C to +70°C
Storage Temperature (plastic)	-55°C to +150°C
Power Dissipation	1W
Short Circuit Output Current	50mA

*Stresses greater than those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC ELECTRICAL CHARACTERISTICS AND OPERATING CONDITIONS

(Notes: 1, 3, 5, 6, 7) (V_{CC} = +5V ±10%)

PARAMETER/CONDITION	SYMBOL	MIN	MAX	UNITS	NOTES
Supply Voltage	V _{CC}	4.5	5.5	V	
Input High (Logic 1) Voltage, all inputs	V _{IH}	2.4	V _{CC} +1	V	
Input Low (Logic 0) Voltage, all inputs	V _{IL}	-1.0	0.8	V	
INPUT LEAKAGE CURRENT Any input 0V ≤ V _{IN} ≤ V _{CC} +1V (All other pins not under test = 0V)	I _I	-2	2	μA	
OUTPUT LEAKAGE CURRENT (DQ is disabled; 0V ≤ V _{OUT} ≤ 5.5V)	I _{OZ}	-10	10	μA	
OUTPUT LEVELS Output High Voltage (I _{OUT} = -5mA)	V _{OH}	2.4		V	
Output Low Voltage (I _{OUT} = 4.2mA)	V _{OL}		0.4	V	

PARAMETER/CONDITION	SYMBOL	MAX	UNITS	NOTES
		-6		
STANDBY CURRENT: (TTL) (RAS# = CAS# = V _{IH})	I _{CC1}	2	mA	
STANDBY CURRENT: (CMOS) (RAS# = CAS# = V _{CC} -0.2V)	I _{CC2}	1	mA	
	I _{CC2} (L only)	200	μA	
OPERATING CURRENT: Random READ/WRITE Average power supply current (RAS#, CAS#, single address cycling: t _{RC} = t _{RC} [MIN])	I _{CC3}	110	mA	3, 23
OPERATING CURRENT: FAST PAGE MODE Average power supply current (RAS# = V _{IL} , CAS#, address cycling: t _{PC} = t _{PC} [MIN])	I _{CC4}	80	mA	3, 23
REFRESH CURRENT: RAS# ONLY Average power supply current (RAS# cycling, CAS# = V _{IH} : t _{RC} = t _{RC} [MIN])	I _{CC5}	110	mA	3, 23
REFRESH CURRENT: CBR Average power supply current (RAS#, CAS#, address cycling: t _{RC} = t _{RC} [MIN])	I _{CC6}	110	mA	3, 4
REFRESH CURRENT: Extended (L version only) Average power supply current during Extended Refresh: CAS# = 0.2V or CBR cycling; RAS# = t _{RAS} (MIN); WE# = V _{CC} -0.2V; A0-A10 and D _{IN} = V _{CC} -0.2V or 0.2V (D _{IN} may be left open); t _{RC} = 125μs (1,024 rows at 125μs = 128ms)	I _{CC7} (L only)	300	μA	3, 4, 6, 21

CAPACITANCE

PARAMETER	SYMBOL	MAX	UNITS	NOTES
Input Capacitance: A0-A10, D	C _{I1}	5	pF	2
Input Capacitance: RAS#, CAS#, WE#	C _{I2}	7	pF	2
Output Capacitance: DQ	C _O	7	pF	2

AC ELECTRICAL CHARACTERISTICS

(Notes: 5, 6, 7, 8, 9, 10, 11, 12) (V_{CC} = +5V ±10%)

AC CHARACTERISTICS		-6			
PARAMETER	SYM	MIN	MAX	UNITS	NOTES
Access time from column address	t ^{AA}		30	ns	
Column-address hold time (referenced to RAS#)	t ^{AR}	45		ns	
Column-address setup time	t ^{ASC}	0		ns	
Row-address setup time	t ^{ASR}	0		ns	
Column-address to WE# delay time	t ^{AWD}	30		ns	18
Access time from CAS#	t ^{CAC}		15	ns	
Column-address hold time	t ^{CAH}	10		ns	
CAS# pulse width	t ^{CAS}	15	10,000	ns	
CAS# hold time (CBR REFRESH)	t ^{CHR}	10		ns	4
CAS# to output in Low-Z	t ^{CLZ}	0		ns	
CAS# precharge time	t ^{CP}	10		ns	13
Access time from CAS# precharge	t ^{CPA}		35	ns	
CAS# to RAS# precharge time	t ^{CRP}	10		ns	
CAS# hold time	t ^{CSH}	60		ns	
CAS# setup time (CBR REFRESH)	t ^{CSR}	10		ns	4
CAS# to WE# delay time	t ^{CWD}	15		ns	18
Write command to CAS# lead time	t ^{CWL}	15		ns	
Data-in hold time	t ^{DH}	10		ns	19
Data-in setup time	t ^{DS}	0		ns	19
Output buffer turn-off delay	t ^{OFF}	3	15	ns	17, 23
FAST-PAGE-MODE READ or WRITE cycle time	t ^{PC}	35		ns	
FAST-PAGE-MODE READ-WRITE cycle time	t ^{PRWC}	60		ns	
Access time from RAS#	t ^{RAC}		60	ns	
RAS# to column-address delay time	t ^{RAD}	15		ns	15
Row-address hold time	t ^{RAH}	10		ns	
RAS# pulse width	t ^{RAS}	60	10,000	ns	21
RAS# pulse width (FAST PAGE MODE)	t ^{RASP}	60	100,000	ns	21
Random READ or WRITE cycle time	t ^{RC}	110		ns	
RAS# to CAS# delay time	t ^{RCD}	20		ns	14
Read command hold time (referenced to CAS#)	t ^{RCH}	0		ns	16
Read command setup time	t ^{RCS}	0		ns	
Refresh period (1,024 cycles)	t ^{REF}		16	ms	
Refresh period (1,024 cycles) L version	t ^{REF}		128	ms	
RAS# precharge time	t ^{RP}	40		ns	
RAS# to CAS# precharge time	t ^{RPC}	0		ns	

AC ELECTRICAL CHARACTERISTICS

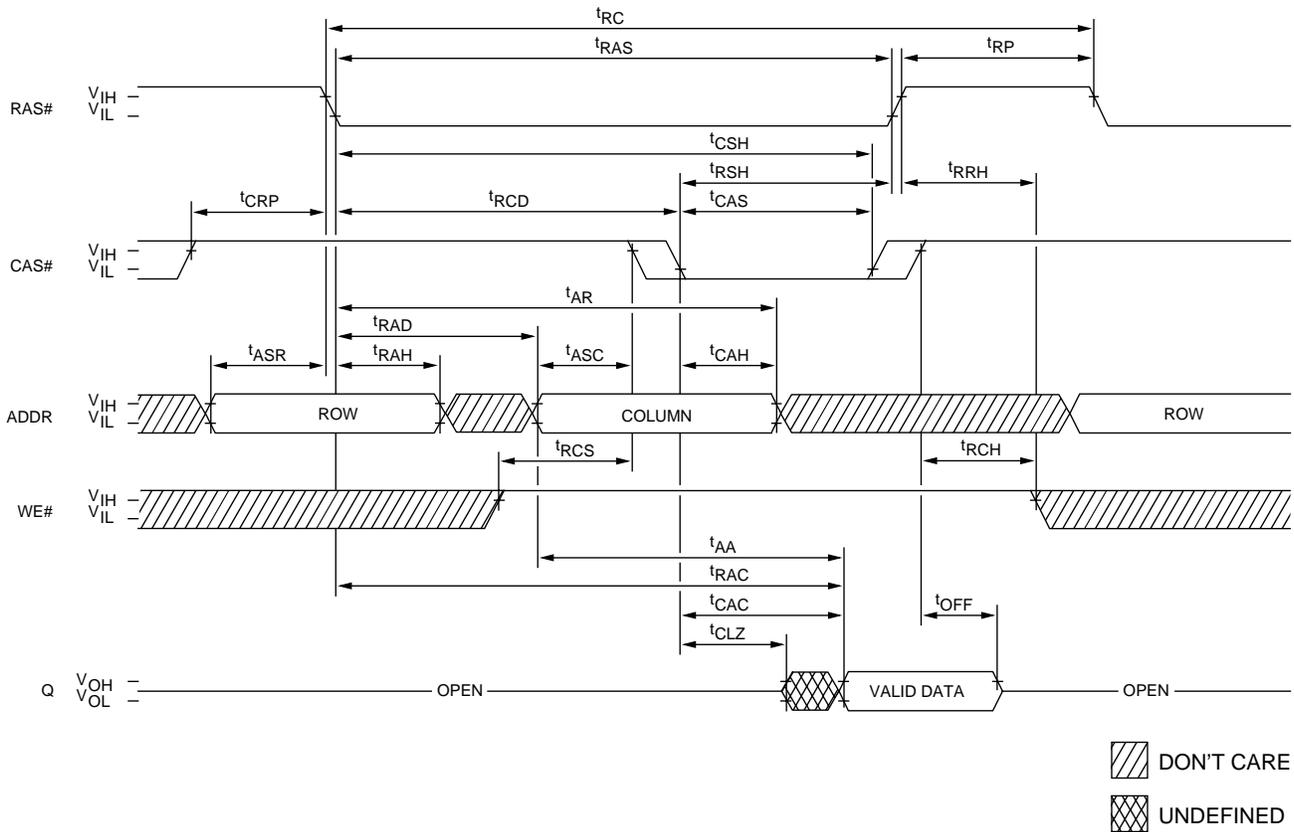
 (Notes: 5, 6, 7, 8, 9, 10, 11, 12) ($V_{CC} = +5V \pm 10\%$)

AC CHARACTERISTICS PARAMETER	SYM	-6		UNITS	NOTES
		MIN	MAX		
Read command hold time (referenced to RAS#)	t_{RRH}	0		ns	16
RAS# hold time	t_{RSH}	15		ns	
READ WRITE cycle time	t_{RWC}	130		ns	
RAS# to WE# delay time	t_{RWD}	60		ns	18
Write command to RAS# lead time	t_{RWL}	15		ns	
Transition time (rise or fall)	t_T	2	50	ns	
Write command hold time	t_{WCH}	10		ns	
Write command hold time (referenced to RAS#)	t_{WCR}	45		ns	
WE# command setup time	t_{WCS}	0		ns	18
Write command pulse width	t_{WP}	10		ns	
WE# hold time (CBR REFRESH)	t_{WRH}	10		ns	
WE# setup time (CBR REFRESH)	t_{WRP}	10		ns	

NOTES

1. All voltages referenced to V_{SS} .
2. This parameter is sampled. $V_{CC} = 4.5V$; $f = 1$ MHz.
3. I_{CC} is dependent on output loading and cycle rates. Specified values are obtained with minimum cycle time and the output open.
4. Enables on-chip refresh and address counters.
5. The minimum specifications are used only to indicate cycle time at which proper operation over the full temperature range ($0^{\circ}C \leq T_A \leq 70^{\circ}C$) is ensured.
6. An initial pause of $100\mu s$ is required after power-up, followed by eight RAS# refresh cycles (RAS# ONLY or CBR with WE# HIGH), before proper device operation is ensured. The eight RAS# cycle wake-ups should be repeated any time the t_{REF} refresh requirement is exceeded.
7. AC characteristics assume $t_T = 5ns$.
8. V_{IH} (MIN) and V_{IL} (MAX) are reference levels for measuring timing of input signals. Transition times are measured between V_{IH} and V_{IL} (or between V_{IL} and V_{IH}).
9. In addition to meeting the transition rate specification, all input signals must transit between V_{IH} and V_{IL} (or between V_{IL} and V_{IH}) in a monotonic manner.
10. If $CAS\# = V_{IH}$, data output is High-Z.
11. If $CAS\# = V_{IL}$, data output may contain data from the last valid READ cycle.
12. Measured with a load equivalent to two TTL gates and $100pF$.
13. If $CAS\#$ is LOW at the falling edge of RAS#, Q will be maintained from the previous cycle. To initiate a new cycle and clear the data-out buffer, $CAS\#$ must be pulsed HIGH for t_{CP} .
14. The t_{RCD} (MAX) limit is no longer specified. t_{RCD} (MAX) was specified as a reference point only. If t_{RCD} was greater than the specified t_{RCD} (MAX) limit, then access time was controlled exclusively by t_{CAC} (t_{RAC} [MIN] no longer applied). With or without the t_{RCD} limit, t_{AA} and t_{CAC} must always be met.
15. The t_{RAD} (MAX) limit is no longer specified. t_{RAD} (MAX) was specified as a reference point only. If t_{RAD} was greater than the specified t_{RAD} (MAX) limit, then access time was controlled exclusively by t_{AA} (t_{RAC} and t_{CAC} no longer applied). With or without the t_{RAD} (MAX) limit, t_{AA} , t_{RAC} and t_{CAC} must always be met.
16. Either t_{RCH} or t_{RRH} must be satisfied for a READ cycle.
17. t_{OFF} (MAX) defines the time at which the output achieves the open circuit condition and is not referenced to V_{OH} or V_{OL} .
18. t_{WCS} , t_{RWD} , t_{AWD} and t_{CWD} are restrictive operating parameters in LATE WRITE, READ WRITE and READ-MODIFY-WRITE cycles only. If $t_{WCS} \geq t_{WCS}$ (MIN), the cycle is an EARLY WRITE cycle and the data output will remain an open circuit through-out the entire cycle. If $t_{RWD} \geq t_{RWD}$ (MIN), $t_{AWD} \geq t_{AWD}$ (MIN) and $t_{CWD} \geq t_{CWD}$ (MIN), the cycle is a READ WRITE and the data output will contain data read from the selected cell. If neither of the above conditions is met, the cycle is a LATE WRITE and the state of data-out is indeterminate (at access time and until $CAS\#$ goes back to V_{IH}).
19. These parameters are referenced to $CAS\#$ leading edge in early WRITE cycles and $WE\#$ leading edge in late WRITE or READ WRITE cycles.
20. A HIDDEN REFRESH may also be performed after a WRITE cycle. In this case, $WE\# = LOW$.
21. Extended refresh current is reduced as t_{RAS} is reduced from its maximum specification during the extended refresh cycle.
22. The 3ns minimum is a parameter guaranteed by design.
23. Column address changed once each cycle.

READ CYCLE



TIMING PARAMETERS

SYMBOL	-6		UNITS
	MIN	MAX	
t_{AA}		30	ns
t_{AR}	45		ns
t_{ASC}	0		ns
t_{ASR}	0		ns
t_{CAC}		15	ns
t_{CAH}	10		ns
t_{CAS}	15	10,000	ns
t_{CLZ}	0		ns
t_{CRP}	10		ns
t_{CSH}	60		ns
t_{OFF}	3	15	ns

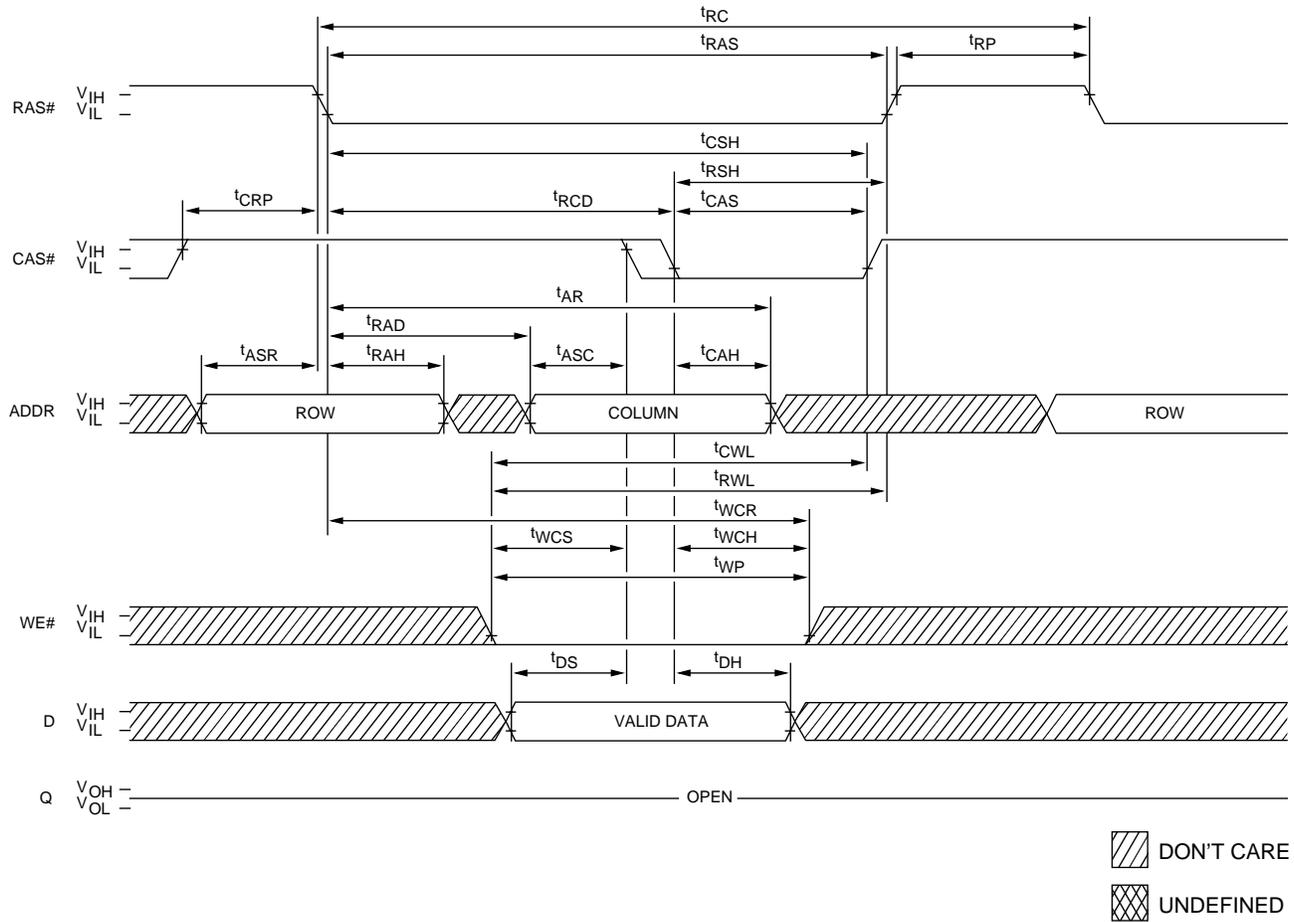
SYMBOL	-6		UNITS
	MIN	MAX	
t_{RAC}		60	ns
t_{RAD}	15		ns
t_{RAH}	10		ns
t_{RAS}	60	10,000	ns
t_{RC}	110		ns
t_{RCD}	20		ns
t_{RCH}	0		ns
t_{RCS}	0		ns
t_{RP}	40		ns
t_{RRH}	0		ns
t_{RSH}	15		ns

OBSOLETE



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EARLY WRITE CYCLE

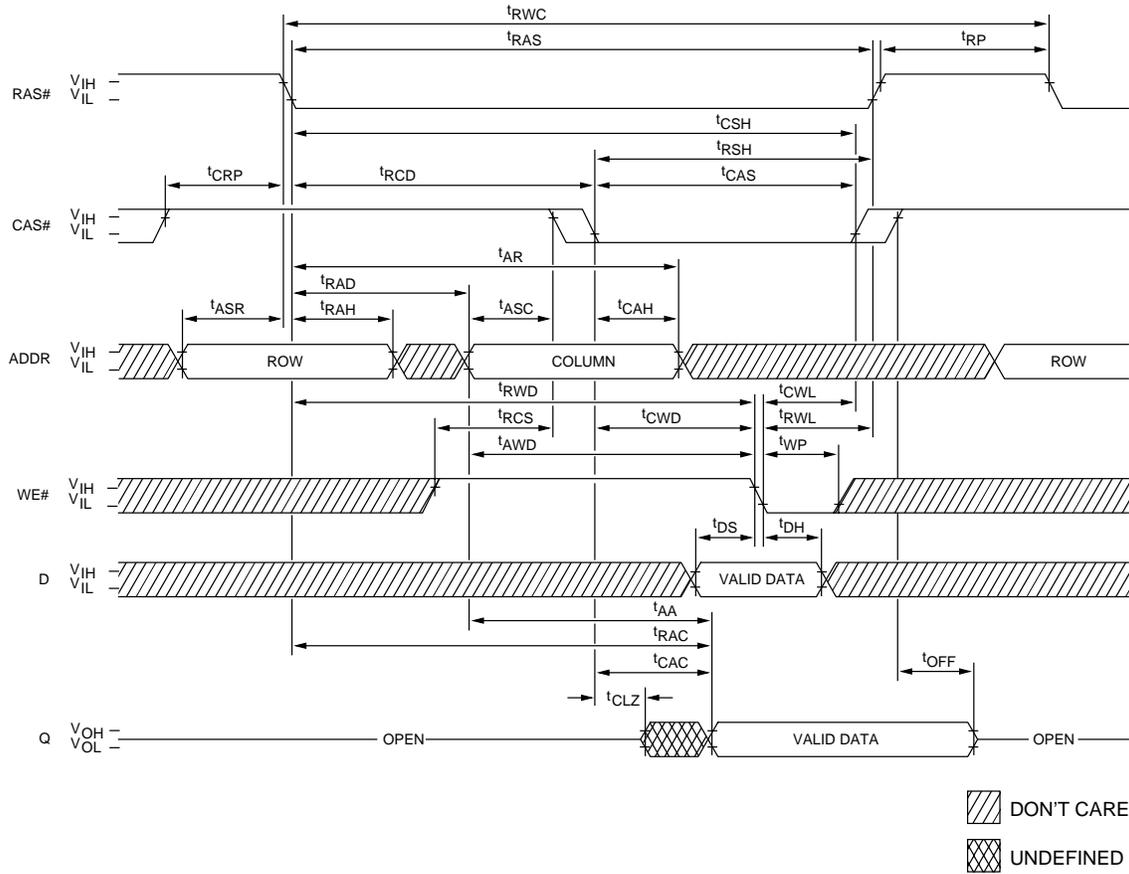


TIMING PARAMETERS

SYMBOL	-6		UNITS
	MIN	MAX	
t_{AR}	45		ns
t_{ASC}	0		ns
t_{ASR}	0		ns
t_{CAH}	10		ns
t_{CAS}	15	10,000	ns
t_{CRP}	10		ns
t_{CSH}	60		ns
t_{CWL}	15		ns
t_{DH}	10		ns
t_{DS}	0		ns
t_{RAD}	15		ns

SYMBOL	-6		UNITS
	MIN	MAX	
t_{RAH}	10		ns
t_{RAS}	60	10,000	ns
t_{RC}	110		ns
t_{RCD}	20		ns
t_{RP}	40		ns
t_{RSH}	15		ns
t_{RWL}	15		ns
t_{WCH}	10		ns
t_{WCR}	45		ns
t_{WCS}	0		ns
t_{WP}	10		ns

READ WRITE CYCLE
(LATE WRITE and READ-MODIFY-WRITE cycles)

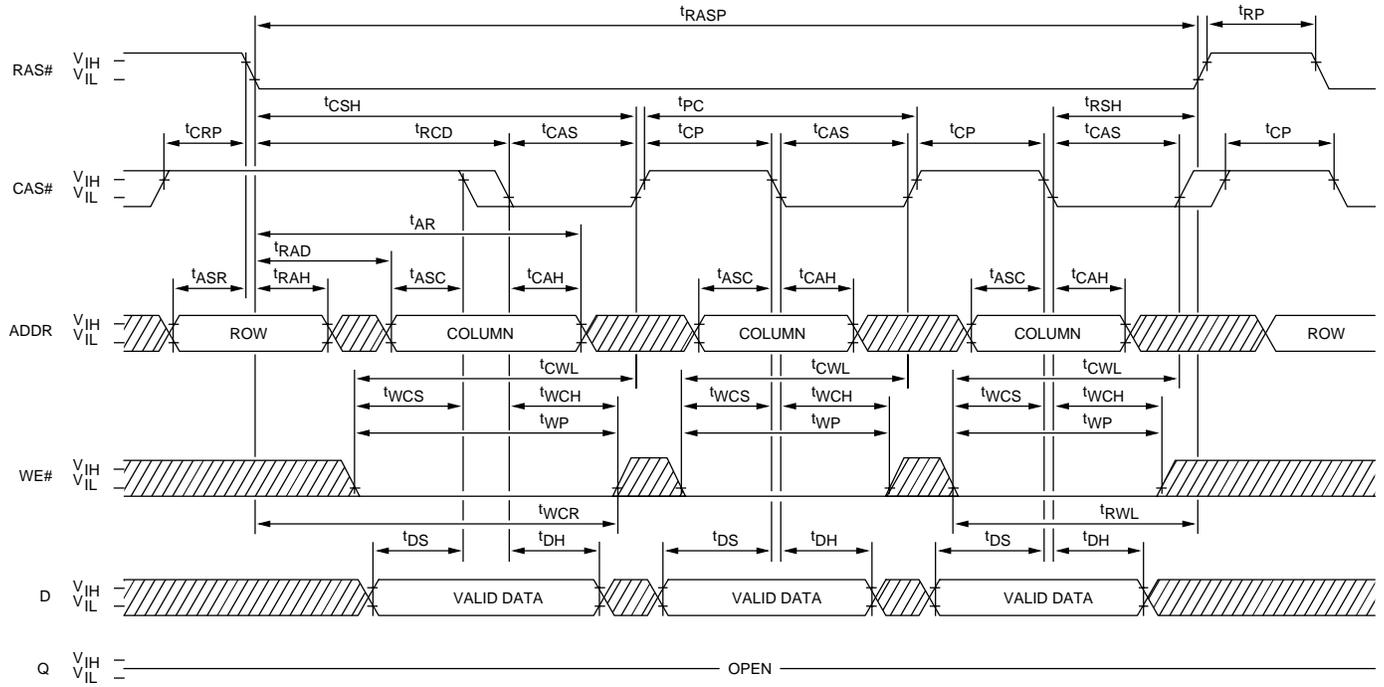


TIMING PARAMETERS

SYMBOL	-6		UNITS
	MIN	MAX	
t_{AA}		30	ns
t_{AR}	45		ns
t_{ASC}	0		ns
t_{ASR}	0		ns
t_{AWD}	30		ns
t_{CAC}		15	ns
t_{CAH}	10		ns
t_{CAS}	15	10,000	ns
t_{CLZ}	0		ns
t_{CRP}	10		ns
t_{CSH}	60		ns
t_{CWD}	15		ns
t_{CWL}	15		ns
t_{DH}	10		ns

SYMBOL	-6		UNITS
	MIN	MAX	
t_{DS}	0		ns
t_{OFF}	3	15	ns
t_{RAC}		60	ns
t_{RAD}	15		ns
t_{RAH}	10		ns
t_{RAS}	60	10,000	ns
t_{RCD}	20		ns
t_{RCS}	0		ns
t_{RP}	40		ns
t_{RSH}	15		ns
t_{RWC}	130		ns
t_{RWD}	60		ns
t_{RWL}	15		ns
t_{WP}	10		ns

FAST-PAGE-MODE EARLY-WRITE CYCLE



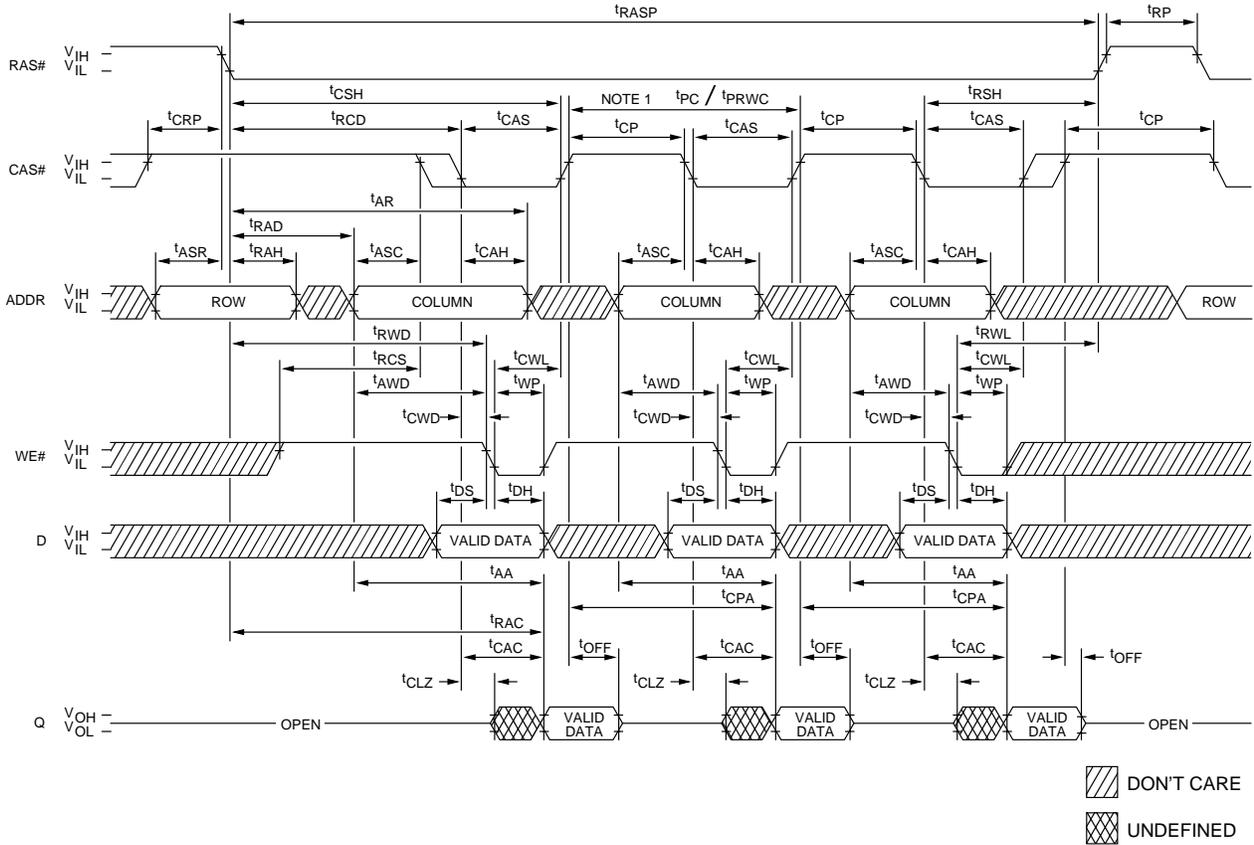
DON'T CARE
 UNDEFINED

TIMING PARAMETERS

SYMBOL	-6		UNITS
	MIN	MAX	
t_{AR}	45		ns
t_{ASC}	0		ns
t_{ASR}	0		ns
t_{CAH}	10		ns
t_{CAS}	15	10,000	ns
t_{CP}	10		ns
t_{CRP}	10		ns
t_{CSH}	60		ns
t_{CWL}	15		ns
t_{DH}	10		ns
t_{DS}	0		ns
t_{PC}	35		ns

SYMBOL	-6		UNITS
	MIN	MAX	
t_{RAD}	15		ns
t_{RAH}	10		ns
t_{RASP}	60	100,000	ns
t_{RCD}	20		ns
t_{RP}	40		ns
t_{RSH}	15		ns
t_{RSL}	15		ns
t_{WCH}	10		ns
t_{WCR}	45		ns
t_{WCS}	0		ns
t_{WP}	10		ns

FAST-PAGE-MODE READ-WRITE CYCLE
(LATE WRITE and READ-MODIFY-WRITE cycles)



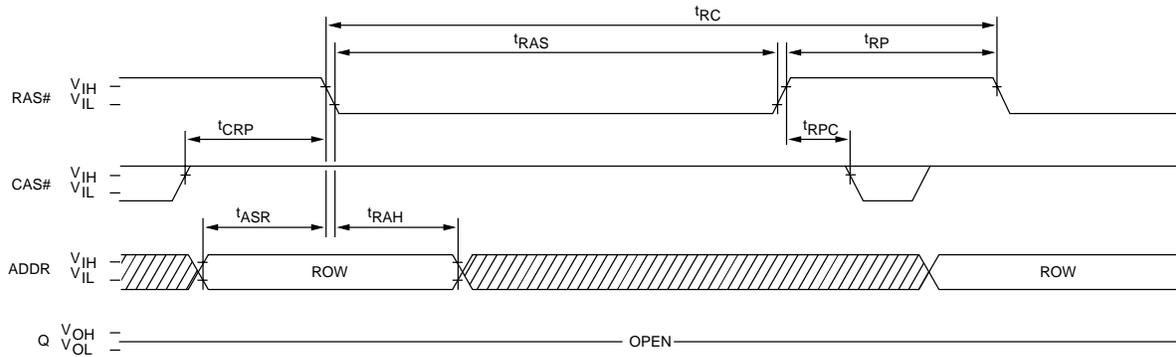
TIMING PARAMETERS

SYMBOL	-6		UNITS
	MIN	MAX	
t_{AA}		30	ns
t_{AR}	45		ns
t_{ASC}	0		ns
t_{ASR}	0		ns
t_{AWD}	30		ns
t_{CAC}		15	ns
t_{CAH}	10		ns
t_{CAS}	15	10,000	ns
t_{CLZ}	0		ns
t_{CP}	10		ns
t_{CPA}		35	ns
t_{CRP}	10		ns
t_{CSH}	60		ns
t_{CWD}	15		ns
t_{CWL}	15		ns
t_{DH}	10		ns

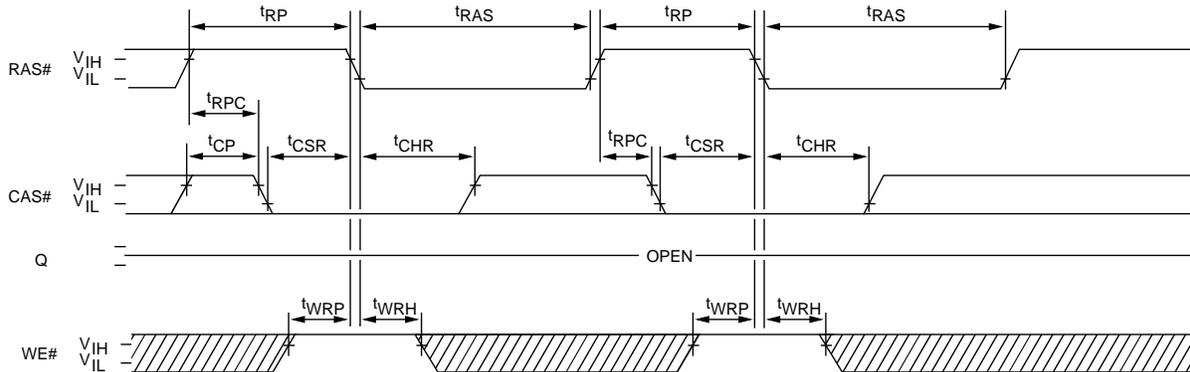
SYMBOL	-6		UNITS
	MIN	MAX	
t_{DS}	0		ns
t_{OFF}	3	15	ns
t_{PC}	35		ns
t_{PRWC}	60		ns
t_{RAC}		60	ns
t_{RAD}	15		ns
t_{RAH}	10		ns
t_{RASP}	60	100,000	ns
t_{RCD}	20		ns
t_{RCS}	0		ns
t_{RP}	40		ns
t_{RSH}	15		ns
t_{RWD}	60		ns
t_{RWL}	15		ns
t_{WP}	10		ns

NOTE: 1. t_{PC} is for LATE WRITE only.

RAS#-ONLY REFRESH CYCLE
(WE# and A10 = DON'T CARE)



CBR REFRESH CYCLE
(Addresses = DON'T CARE)



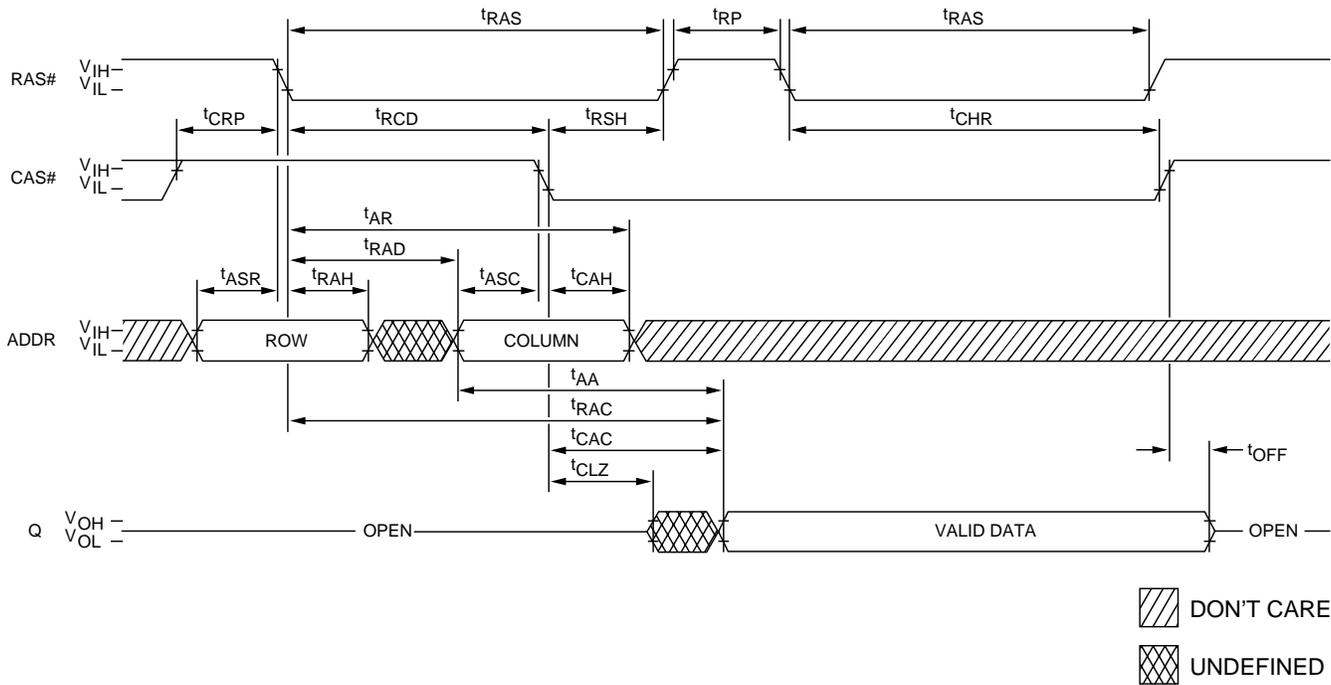
DON'T CARE
 UNDEFINED

TIMING PARAMETERS

SYMBOL	-6		UNITS
	MIN	MAX	
t ^{ASR}	0		ns
t ^{CHR}	10		ns
t ^{CP}	10		ns
t ^{CRP}	10		ns
t ^{CSR}	10		ns
t ^{RAH}	10		ns

SYMBOL	-6		UNITS
	MIN	MAX	
t ^{RAS}	60	10,000	ns
t ^{RC}	110		ns
t ^{RP}	40		ns
t ^{RPC}	0		ns
t ^{WRH}	10		ns
t ^{WRP}	10		ns

HIDDEN REFRESH CYCLE²⁰
(WE# = HIGH)



TIMING PARAMETERS

SYMBOL	-6		UNITS
	MIN	MAX	
t _{AA}		30	ns
t _{AR}	45		ns
t _{ASC}	0		ns
t _{ASR}	0		ns
t _{CAC}		15	ns
t _{CAH}	10		ns
t _{CHR}	10		ns
t _{CLZ}	0		ns
t _{CRP}	10		ns

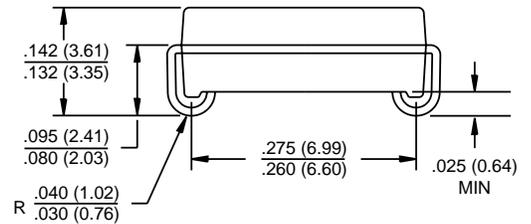
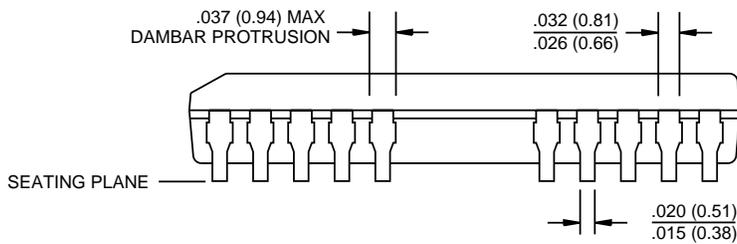
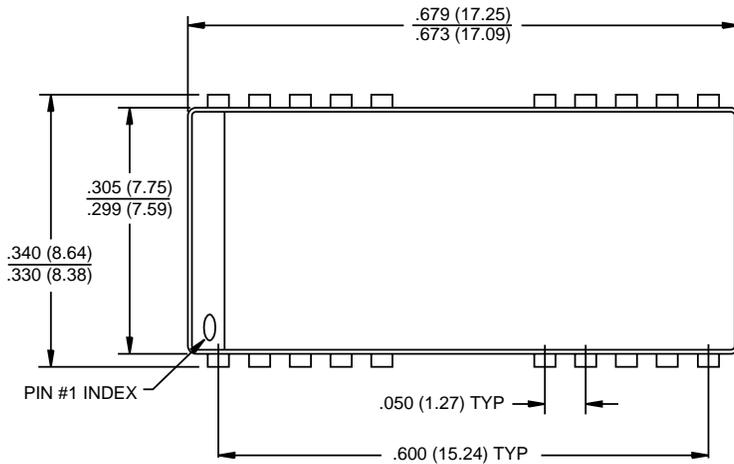
SYMBOL	-6		UNITS
	MIN	MAX	
t _{OFF}	3	15	ns
t _{RAC}		60	ns
t _{RAD}	15		ns
t _{RAH}	10		ns
t _{RAS}	60	10,000	ns
t _{RCD}	20		ns
t _{RP}	40		ns
t _{RSH}	15		ns

OBSOLETE



4 MEG x 1
FPM DRAM

20/26-PIN PLASTIC SOJ (300 mil)



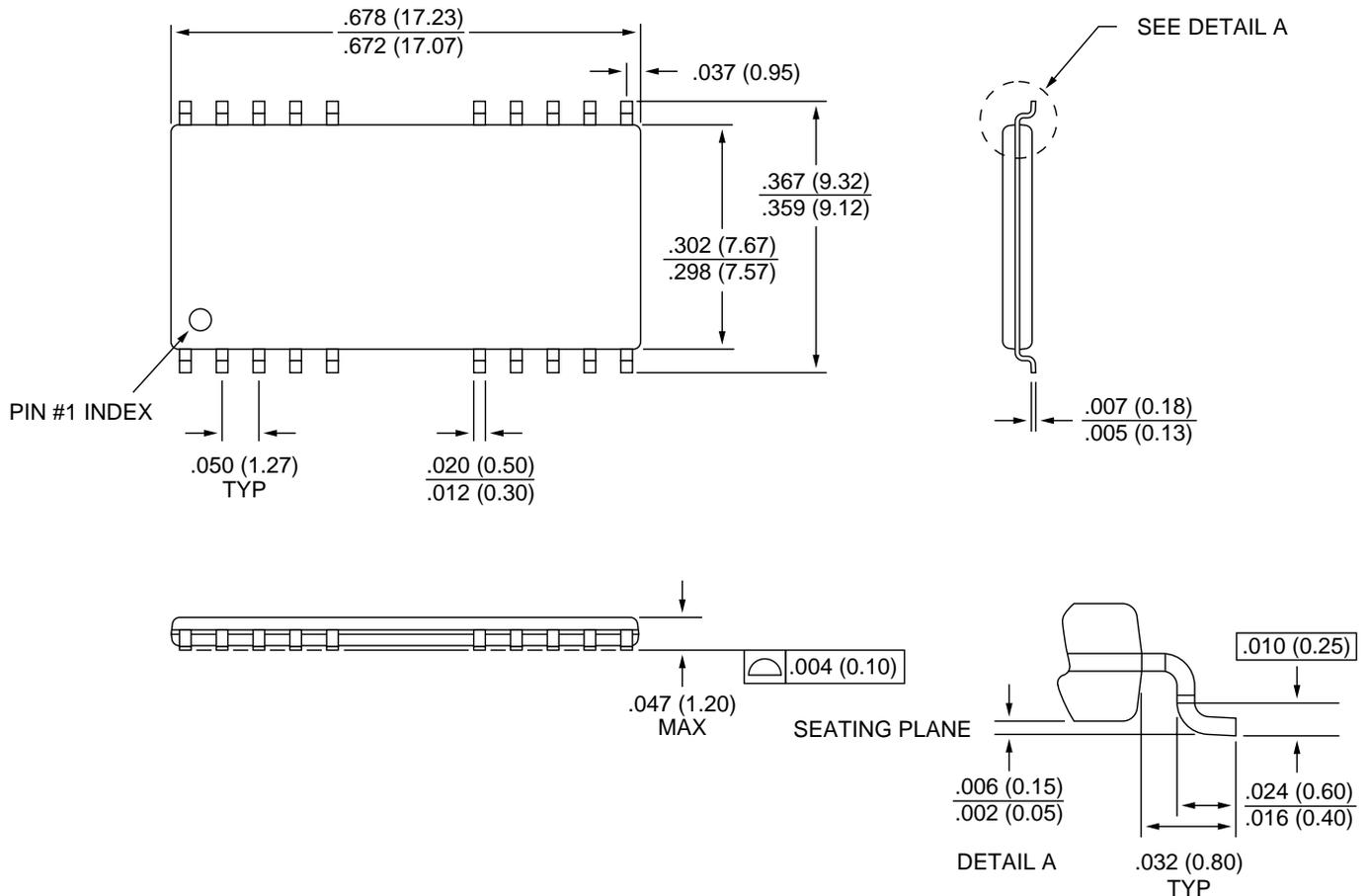
- NOTE:**
1. All dimensions in inches (millimeters) $\frac{\text{MAX}}{\text{MIN}}$ or typical where noted.
 2. Package width and length do not include mold protrusion; allowable mold protrusion is $.01$ " per side.

OBSOLETE



4 MEG x 1 FPM DRAM

20/26-PIN PLASTIC TSOP (300 mil)



- NOTE:**
1. All dimensions in inches (millimeters) $\frac{\text{MAX}}{\text{MIN}}$ or typical where noted.
 2. Package width and length do not include mold protrusion; allowable mold protrusion is .01" per side.



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